New Release

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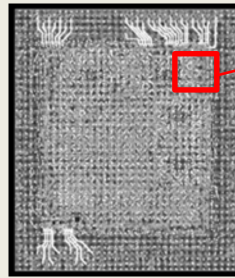
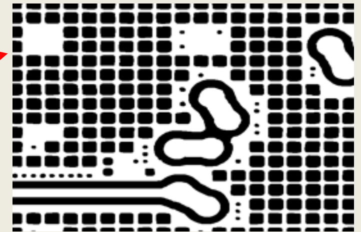
Apple A10 (iPhone7) Package Analysis

March, 2017. Using its proprietary delayering and high quality digitization technology, LTEC Corporation extracted all five RDL layers used in TSMC's InFO package deployed in the A10 processor of Apple's iPhone7. Unlike its flip-chip substrate-based fan-out predecessors, InFO technology relies on multiple Re-Distribution Layers (RDLs) and improved chip alignment accuracy, and it can easily accommodate high I/O count. Even with the five RDLs, package thickness is reduced by 20%. Additional benefits of the technology are 10% lower heat generation and 20% higher I/O speed.

Package (Top)

Package (Bottom)





Digitized RDL3

Partial cross-section

Many more details including cross-sections, Line/Space (L/S), and thickness info of the RDLs are contained in this 77 pages report. Gerber, dxf, PADS (ASCII), and ODB++ files of the RDLs are also available.

Priced to sell at $5,000

Reconstructed layers set in Geber, dxf, PADS (ASCII), or ODB++ format: $1,000

Contact LTEC Corporation

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16G-0011-1

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